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|-------------------------------------------------------------|--|-------------------------|---------------------------|
| U.S. Department of Commerce, Patent and Trademark Office    |  | Bucket No.              | Serial No.                |
| (PTO Form 1449 modified)                                    |  | AMAT/1931.P1            | 10/052,681                |
| <b>LISTS OF PATENTS AND PUBLICATIONS CITED BY APPLICANT</b> |  | Applicant<br>Xi, et al. | Confirmation<br>No.: 4083 |
| (Use several sheets if necessary)                           |  | Filing Date             | Group                     |
| Examiner Unknown                                            |  | January 17, 2002        | 2814                      |

**U.S. Patent Documents**

| Examiner Initial |     | Document Number | Issue Date | Applicant(s) Name  | Class | Subclass | Filing Date If Appropriate |
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| GP               | A16 | 6,157,081       | 12-05-2000 | Nariman, et al.    | 257   | 752      | 03-10-1999                 |
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| GP               | A19 | 6,023,102       | 02-08-2000 | Nguyen, et al.     | 257   | 774      | 10-08-1998                 |
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| GP               | A23 | 5,846,332       | 12-08-1998 | Zhao et al.        | 118   | 728      | 07-12-1996                 |
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| GP               | A25 | 5,654,232       | 08-05-1997 | Gardner            | 438   | 661      | 03-15-1996                 |
| GP               | A26 | 5,613,296       | 03-25-1997 | Kurino et al.      | 29    | 852      | 04-13-1995                 |

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|------------------|----|-----------------|------|---------|-------|----------|-------------|----|
|                  |    |                 |      |         |       |          | YES         | NO |
|                  | B4 |                 |      |         |       |          |             |    |
|                  | B5 |                 |      |         |       |          |             |    |
|                  | B6 |                 |      |         |       |          |             |    |

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| GP               | C5 ✓            | Mikagi H. Ishikawa, T. Usami, M. Suzuki, K. Inoue, N. Oda, S. Chikaki, I. Sakai and T. Kikkawa. "Barrier Metal Free Copper Damascene Interconnection Technology Using Atmospheric Copper Reflow and Nitrogen Doping in SiOF Film. 1996 IEEE. Pp. 365-368 |
| GP               | C6 ✓            | Y. Shacham-Diamand, V. Dubin, and M. Angyal "Electroless Copper Deposition for ULSI" 1995 Elsevier Science S.A., pp. 93-103                                                                                                                              |
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|                  | Date Considered | 6/11/03                                                                                                                                                                                                                                                  |

\*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with your communication to applicant.

|                                                             |  |                         |                           |
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| JP               | A7  | 6,229,174       | 05-08-2001 | Parekh            | 257   | 306      | 12-08-1997                 |
| JP               | A8  | 6,221,775       | 04-24-2001 | Ference, et al.   | 438   | 691      | 09-24-1998                 |
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| JP               | A10 | 6,200,433       | 03-13-2001 | Ding, et al.      | 204   | 192.15   | 11-01-1999                 |
| JP               | A11 | 6,184,138       | 02-06-2001 | Ho, et al.        | 438   | 687      | 09-07-1999                 |
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|                  |    |                                  |            |         |       |          | YES         | NO |
| JP               | B1 | JP 08-213,119<br>Abstract Only ✓ | 07-24-1996 | JP      | H01L  | 21/768   |             | X  |
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| JP               | C2 ✓                    | Gardner et al., "Encapsulated Copper Interconnection Device using Sidewall Barriers", Thin Solid Films 262 (1995) 104-119.                              |
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U.S. Department of Commerce Patent and Trademark Office

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Serial No.

(PTO Form 1449 modified)

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**LISTS OF PATENTS AND PUBLICATIONS CITED BY APPLICANT**Applicant  
Xi, et al.

(Use several sheets if necessary)

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Examiner Unknown

January 17, 2002

Unknown

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| gp               | A28 | 5,534,460       | 07-09-1996 | Tseng et al.      | 437   | 187      | 04-27-1995                 |
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| gp               | A30 | 5,371,042       | 12-06-1994 | Ong               | 437   | 194      | 06-16-1992                 |
| gp               | A31 | 5,354,712       | 10-11-1994 | Ho et al.         | 437   | 195      | 11-12-1992                 |
| gp               | A32 | 5,308,793       | 05-03-1994 | Taguchi et al.    | 437   | 194      | 07-22-1992                 |
| gp               | A33 | 5,186,718       | 02-16-1993 | Tepman, et al.    | 29    | 25.01    | 04-15-1991                 |
| gp               | A34 | 5,178,739       | 01-12-1993 | Barnes et al.     | 204   | 192.12   | 09-25-1991                 |
| gp               | A35 | 4,962,060       | 10-09-1990 | Sliwa, et al.     | 437   | 192      | 05-02-1989                 |
| gp               | A36 | 4,951,601       | 08-28-1990 | Maydan, et al.    | 118   | 719      | 06-23-1989                 |
|                  | A37 |                 |            |                   |       |          |                            |
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|                  |     |                 |      |         |       |          | YES         | NO |
|                  | B07 |                 |      |         |       |          |             |    |
|                  | B08 |                 |      |         |       |          |             |    |
|                  | B09 |                 |      |         |       |          |             |    |

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| gp               | C8                      | Electromigration Failure Distributions for Multi-Large Interconnects as a Function of Line Width Experiments and Simulation, D.D. Brown, J.E. Sanchez, Jr., V. Pham, P.R. Besser, M.A. Korhonen, and C.Y. Li, Mat Res. Soc. Symp. Vol 427 |
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| Examiner         | Date Considered 6/11/03 |                                                                                                                                                                                                                                           |

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